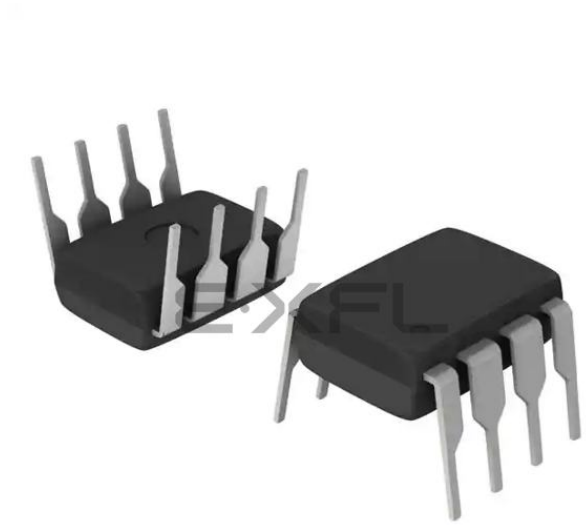

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	6
Program Memory Size	1.75KB (1K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 5.5V
Data Converters	A/D 4x10b; D/A 1x5b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	8-DIP (0.300", 7.62mm)
Supplier Device Package	8-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic12f1571-i-p

2.1 Automatic Interrupt Context Saving

During interrupts, certain registers are automatically saved in shadow registers and restored when returning from the interrupt. This saves stack space and user code. See **Section 7.5 "Automatic Context Saving"**, for more information.

2.2 16-Level Stack with Overflow and Underflow

These devices have a hardware stack memory, 15 bits wide and 16 words deep. A Stack Overflow or Underflow will set the appropriate bit (STKOVF or STKUNF) in the PCON register, and if enabled, will cause a Software Reset. See **Section 3.5 "Stack"** for more details.

2.3 File Select Registers

There are two 16-bit File Select Registers (FSR). FSRs can access all file registers and program memory, which allows one Data Pointer for all memory. When an FSR points to program memory, there is one additional instruction cycle in instructions using INDF to allow the data to be fetched. General purpose memory can now also be addressed linearly, providing the ability to access contiguous data larger than 80 bytes. There are also new instructions to support the FSRs. See **Section 3.6 "Indirect Addressing"** for more details.

2.4 Instruction Set

There are 49 instructions for the enhanced mid-range CPU to support the features of the CPU. See **Section 25.0 "Instruction Set Summary"** for more details.

TABLE 3-10: SPECIAL FUNCTION REGISTER SUMMARY (CONTINUED)

Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on All Other Resets
Bank 31											
F8Ch — FE3h	—	Unimplemented								—	—
FE4h	STATUS_ SHAD	—	—	—	—	—	Z_SHAD	DC_SHAD	C_SHAD	---- -xxx	---- -uuu
FE5h	WREG_ SHAD	Working Register Shadow								xxxx xxxx	uuuu uuuu
FE6h	BSR_ SHAD	—	—	—	Bank Select Register Shadow					---x xxxx	---u uuuu
FE7h	PCLATH_ SHAD	—	Program Counter Latch High Register Shadow							-xxx xxxx	uuuu uuuu
FE8h	FSR0L_ SHAD	Indirect Data Memory Address 0 Low Pointer Shadow								xxxx xxxx	uuuu uuuu
FE9h	FSR0H_ SHAD	Indirect Data Memory Address 0 High Pointer Shadow								xxxx xxxx	uuuu uuuu
FEAh	FSR1L_ SHAD	Indirect Data Memory Address 1 Low Pointer Shadow								xxxx xxxx	uuuu uuuu
FEBh	FSR1H_ SHAD	Indirect Data Memory Address 1 High Pointer Shadow								xxxx xxxx	uuuu uuuu
FECh	—	Unimplemented								—	—
FEDh	STKPTR	—	—	—	Current Stack Pointer					---1 1111	---1 1111
FEEh	TOSL	Top-of-Stack Low Byte								xxxx xxxx	uuuu uuuu
FEFh	TOSH	—	Top-of-Stack High Byte							-xxx xxxx	-uuu uuuu

Legend: x = unknown; u = unchanged; q = value depends on condition; — = unimplemented; r = reserved. Shaded locations are unimplemented, read as '0'.

Note 1: PIC12F1571/2 only.

2: PIC12(L)F1572 only.

3: Unimplemented, read as '1'.

4.2 Register Definitions: Configuration Words

REGISTER 4-1: CONFIG1: CONFIGURATION WORD 1

U-1	U-1	R/P-1	R/P-1	R/P-1	U-1
—	—	$\overline{\text{CLKOUTEN}}$	BOREN<1:0>(1)		—
bit 13					bit 8

R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	U-1	R/P-1	R/P-1
$\overline{\text{CP}}$(2)	MCLRE	$\overline{\text{PWRTE}}$(1)	WDTE<1:0>		—	FOSC<1:0>	
bit 7							bit 0

Legend:		
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '1'
'0' = Bit is cleared	'1' = Bit is set	n = Value when blank or after bulk erase

bit 13-12 **Unimplemented:** Read as '1'

bit 11 **$\overline{\text{CLKOUTEN}}$:** Clock Out Enable bit
1 = Off – CLKOUT function is disabled; I/O or oscillator function on CLKOUT pin
0 = On – CLKOUT function is enabled on CLKOUT pin

bit 10-9 **BOREN<1:0>:** Brown-out Reset Enable bits(1)
11 = On – Brown-out Reset is enabled; the SBOREN bit is ignored
10 = Sleep – Brown-out Reset is enabled while running and disabled in Sleep; the SBOREN bit is ignored
01 = SBODEN – Brown-out Reset is controlled by the SBOREN bit in the BORCON register
00 = Off – Brown-out Reset is disabled; the SBOREN bit is ignored

bit 8 **Unimplemented:** Read as '1'

bit 7 **$\overline{\text{CP}}$:** Flash Program Memory Code Protection bit(2)
1 = Off – Code protection is off; program memory can be read and written
0 = On – Code protection is on; program memory cannot be read or written externally

bit 6 **MCLRE:** $\overline{\text{MCLR}}$/VPP Pin Function Select bit
If LVP bit = 1 (On):
This bit is ignored. $\overline{\text{MCLR}}$/VPP pin function is $\overline{\text{MCLR}}$; weak pull-up is enabled.
If LVP bit = 0 (Off):
1 = On – $\overline{\text{MCLR}}$/VPP pin function is $\overline{\text{MCLR}}$; weak pull-up is enabled
0 = Off – $\overline{\text{MCLR}}$/VPP pin function is a digital input, $\overline{\text{MCLR}}$ is internally disabled; weak pull-up is under control of pin's WPU control bit

bit 5 **$\overline{\text{PWRTE}}$:** Power-up Timer Enable bit(1)
1 = Off – PWRT is disabled
0 = On – PWRT is enabled

bit 4-3 **WDTE<1:0>:** Watchdog Timer Enable bits
11 = On – WDT is enabled; SWDTEN is ignored
10 = Sleep – WDT is enabled while running and disabled in Sleep; SWDTEN is ignored
01 = SWDTEN – WDT is controlled by the SWDTEN bit in the WDTCON register
00 = Off – WDT is disabled; SWDTEN is ignored

bit 2 **Unimplemented:** Read as '1'

bit 1-0 **FOSC<1:0>:** Oscillator Selection bits
11 = ECH – External Clock, High-Power mode: CLKI on CLKI
10 = ECM – External Clock, Medium Power mode: CLKI on CLKI
01 = ECL – External Clock, Low-Power mode: CLKI on CLKI
00 = INTOSC – I/O function on CLKI

Note 1: Enabling Brown-out Reset does not automatically enable the Power-up Timer.
2: Once enabled, code-protect can only be disabled by bulk erasing the device.

10.2.4 WRITING TO FLASH PROGRAM MEMORY

Program memory is programmed using the following steps:

1. Load the address in PMADRH:PMADRL of the row to be programmed.
2. Load each write latch with data.
3. Initiate a programming operation.
4. Repeat Steps 1 through 3 until all data is written.

Before writing to program memory, the word(s) to be written must be erased or previously unwritten. Program memory can only be erased one row at a time. No automatic erase occurs upon the initiation of the write.

Program memory can be written one or more words at a time. The maximum number of words written at one time is equal to the number of write latches. See Figure 10-5 (row writes to program memory with 16 write latches) for more details.

The write latches are aligned to the Flash row address boundary defined by the upper 11 bits of PMADRH:PMADRL (PMADRH<6:0>:PMADRL<7:4>), with the lower 4 bits of PMADRL (PMADRL<3:0>) determining the write latch being loaded. Write operations do not cross these boundaries. At the completion of a program memory write operation, the data in the write latches is reset to contain 0x3FFF.

The following steps should be completed to load the write latches and program a row of program memory. These steps are divided into two parts. First, each write latch is loaded with data from the PMDATH:PMDATL using the unlock sequence with LWLO = 1. When the last word to be loaded into the write latch is ready, the LWLO bit is cleared and the unlock sequence executed. This initiates the programming operation, writing all the latches into Flash program memory.

Note:	The special unlock sequence is required to load a write latch with data or initiate a Flash programming operation. If the unlock sequence is interrupted, writing to the latches or program memory will not be initiated.

1. Set the WREN bit of the PMCON1 register.
2. Clear the CFGS bit of the PMCON1 register.
3. Set the LWLO bit of the PMCON1 register. When the LWLO bit of the PMCON1 register is '1', the write sequence will only load the write latches and will not initiate the write to Flash program memory.
4. Load the PMADRH:PMADRL register pair with the address of the location to be written.
5. Load the PMDATH:PMDATL register pair with the program memory data to be written.
6. Execute the unlock sequence (**Section 10.2.2 "Flash Memory Unlock Sequence"**). The write latch is now loaded.
7. Increment the PMADRH:PMADRL register pair to point to the next location.
8. Repeat Steps 5 through 7 until all but the last write latch has been loaded.
9. Clear the LWLO bit of the PMCON1 register. When the LWLO bit of the PMCON1 register is '0', the write sequence will initiate the write to Flash program memory.
10. Load the PMDATH:PMDATL register pair with the program memory data to be written.
11. Execute the unlock sequence (**Section 10.2.2 "Flash Memory Unlock Sequence"**). The entire program memory latch content is now written to Flash program memory.

Note:	The program memory write latches are reset to the blank state (0x3FFF) at the completion of every write or erase operation. As a result, it is not necessary to load all the program memory write latches. Unloaded latches will remain in the blank state.

An example of the complete write sequence is shown in Example 10-3. The initial address is loaded into the PMADRH:PMADRL register pair; the data is loaded using Indirect Addressing.

TABLE 15-1: ADC CLOCK PERIOD (T_{AD}) VS. DEVICE OPERATING FREQUENCIES

ADC Clock Period (T_{AD})		Device Frequency (F_{OSC})				
ADC Clock Source	ADCS<2:0>	20 MHz	16 MHz	8 MHz	4 MHz	1 MHz
Fosc/2	000	100 ns	125 ns	250 ns	500 ns	2.0 μs
Fosc/4	100	200 ns	250 ns	500 ns	1.0 μs	4.0 μs
Fosc/8	001	400 ns	500 ns	1.0 μs	2.0 μs	8.0 μs
Fosc/16	101	800 ns	1.0 μs	2.0 μs	4.0 μs	16.0 μs
Fosc/32	010	1.6 μs	2.0 μs	4.0 μs	8.0 μs	32.0 μs
Fosc/64	110	3.2 μs	4.0 μs	8.0 μs	16.0 μs	64.0 μs
FRC	x11	1.0-6.0 μs	1.0-6.0 μs	1.0-6.0 μs	1.0-6.0 μs	1.0-6.0 μs

Legend: Shaded cells are outside of recommended range.

Note: The T_{AD} period when using the FRC clock source can fall within a specified range (see T_{AD} parameter). The T_{AD} period when using the F_{OSC}-based clock source can be configured for a more precise T_{AD} period. However, the FRC clock source must be used when conversions are to be performed with the device in Sleep mode.

FIGURE 15-2: ANALOG-TO-DIGITAL CONVERSION T_{AD} CYCLES

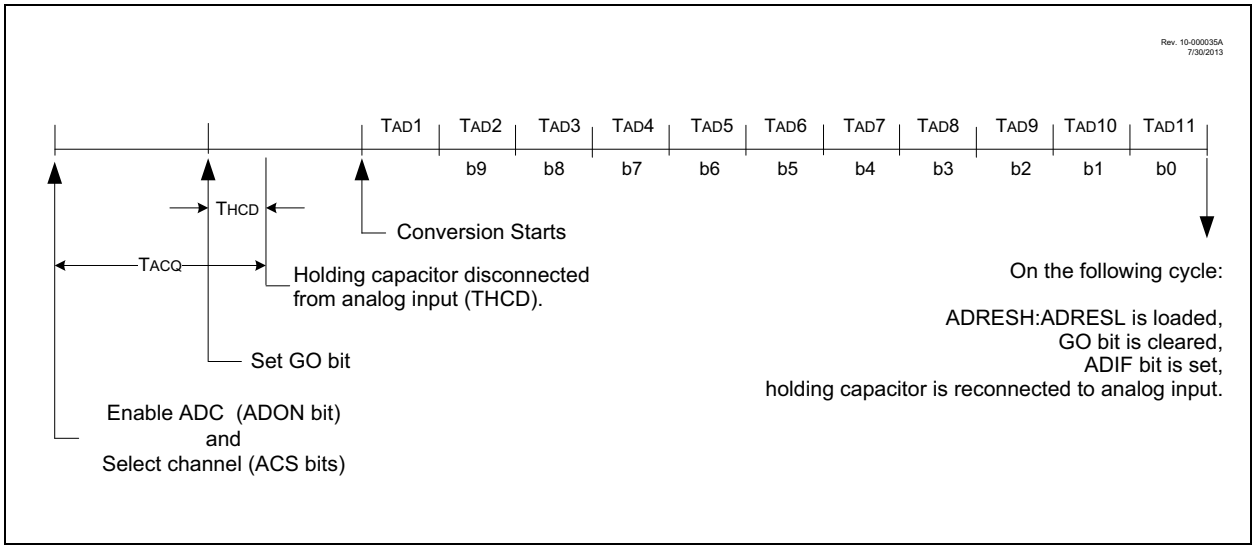


TABLE 15-3: SUMMARY OF REGISTERS ASSOCIATED WITH ADC

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ADCON0	—	CHS<4:0>					GO/$\overline{\text{DONE}}$	ADON	135
ADCON1	ADFM	ADCS<2:0>			—	—	ADPREF<1:0>		136
ADCON2	TRIGSEL<3:0>				—	—	—	—	137
ADRESH	ADC Result Register High								138, 139
ADRESL	ADC Result Register Low								138, 139
ANSELA	—	—	—	ANSA4	—	ANSA<2:0>			114
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	74
PIE1	TMR1GIE	ADIE	RCIE(2)	TXIE(2)	—	—	TMR2IE	TMR1IE	75
PIR1	TMR1GIF	ADIF	RCIF(2)	TXIF(2)	—	—	TMR2IF	TMR1IF	78
TRISA	—	—	TRISA5	TRISA4	—(1)	TRISA<2:0>			113
FVRCON	FVREN	FVRRDY	TSEN	TSRNG	CDAFVR<1:0>		ADFVR<1:0>		125

Legend: — = unimplemented, read as '0'. Shaded cells are not used for the ADC module.

Note 1: Unimplemented, read as '1'.

2: PIC12(L)F1572 only.

19.8 Register Definitions: Timer1 Control

REGISTER 19-1: T1CON: TIMER1 CONTROL REGISTER

R/W-0/u	R/W-0/u	R/W-0/u	R/W-0/u	U-0	R/W-0/u	U-0	R/W-0/u
TMR1CS<1:0>		T1CKPS<1:0>		—	$\overline{\text{T1SYNC}}$	—	TMR1ON
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	
u = Bit is unchanged	x = Bit is unknown	U = Unimplemented bit, read as ‘0’
‘1’ = Bit is set	‘0’ = Bit is cleared	-n/n = Value at POR and BOR/Value at all other Resets

bit 7-6 **TMR1CS<1:0>:** Timer1 Clock Source Select bits
- 11 = Timer1 clock source is the LFINTOSC
- 10 = Timer1 clock source is the T1CKI pin (on the rising edge)
- 01 = Timer1 clock source is the system clock (FOSC)
- 00 = Timer1 clock source is the instruction clock (FOSC/4)

bit 5-4 **T1CKPS<1:0>:** Timer1 Input Clock Prescale Select bits
- 11 = 1:8 Prescale value
- 10 = 1:4 Prescale value
- 01 = 1:2 Prescale value
- 00 = 1:1 Prescale value

bit 3 **Unimplemented:** Read as ‘0’

bit 2 **$\overline{\text{T1SYNC}}$:** Timer1 Synchronization Control bit
- 1 = Does not synchronize the asynchronous clock input
- 0 = Synchronizes the asynchronous clock input with the system clock (FOSC)

bit 1 **Unimplemented:** Read as ‘0’

bit 0 **TMR1ON:** Timer1 On bit
- 1 = Enables Timer1
- 0 = Stops Timer1 and clears Timer1 gate flip-flop

NOTES:

REGISTER 21-2: RCSTA: RECEIVE STATUS AND CONTROL REGISTER

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R-0/0	R-0/0	R-0/0
SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	
u = Bit is unchanged	x = Bit is unknown	U = Unimplemented bit, read as ‘0’
‘1’ = Bit is set	‘0’ = Bit is cleared	-n/n = Value at POR and BOR/Value at all other Resets

bit 7 **SPEN:** Serial Port Enable bit

1 = Serial port is enabled (configures RX/DT and TX/CK pins as serial port pins)
0 = Serial port is disabled (held in Reset)

bit 6 **RX9:** 9-Bit Receive Enable bit

1 = Selects 9-bit reception
0 = Selects 8-bit reception

bit 5 **SREN:** Single Receive Enable bit

Asynchronous mode:
Don’t care.

Synchronous mode – Master:
1 = Enables single receive
0 = Disables single receive
This bit is cleared after reception is complete.

Synchronous mode – Slave:
Don’t care.

bit 4 **CREN:** Continuous Receive Enable bit

Asynchronous mode:
1 = Enables receiver
0 = Disables receiver

Synchronous mode:
1 = Enables continuous receive until enable bit CREN is cleared (CREN overrides SREN)
0 = Disables continuous receive

bit 3 **ADDEN:** Address Detect Enable bit

Asynchronous mode 9-bit (RX9 = 1):
1 = Enables address detection, enables interrupt and loads the receive buffer when RSR<8> is set
0 = Disables address detection, all bytes are received and ninth bit can be used as parity bit

Asynchronous mode 8-bit (RX9 = 0):
Don’t care.

bit 2 **FERR:** Framing Error bit

1 = Framing error (can be updated by reading RCREG register and receiving next valid byte)
0 = No framing error

bit 1 **OERR:** Overrun Error bit

1 = Overrun error (can be cleared by clearing bit, CREN)
0 = No overrun error

bit 0 **RX9D:** Ninth Bit of Received Data bit

This can be address/data bit or a parity bit and must be calculated by user firmware.

21.4.2 AUTO-BAUD OVERFLOW

During the course of Automatic Baud Detection, the ABDOVF bit of the BAUDCON register will be set if the baud rate counter overflows before the fifth rising edge is detected on the RX pin. The ABDOVF bit indicates that the counter has exceeded the maximum count that can fit in the 16 bits of the SPBRGH:SPBRGL register pair. The overflow condition will set the RCIF flag. The counter continues to count until the fifth rising edge is detected on the RX pin. The RCIDL bit will remain false ('0') until the fifth rising edge, at which time, the RDICL bit will set. If the RCREG is read after the overflow occurs, but before the fifth rising edge, the fifth rising edge will set the RCIF again.

Terminating the auto-baud process early to clear an overflow condition will prevent proper detection of the Sync character fifth rising edge. If any falling edges of the Sync character have not yet occurred when the ABDEN bit is cleared, then those will be falsely detected as Start bits. The following steps are recommended to clear the overflow condition:

1. Read RCREG to clear RCIF.
2. If RCIDL is zero, then wait for RCIF and repeat Step 1.
3. Clear the ABDOVF bit.

21.4.3 AUTO-WAKE-UP ON BREAK

During Sleep mode, all clocks to the EUSART are suspended. Because of this, the Baud Rate Generator is inactive and a proper character reception cannot be performed. The auto-wake-up feature allows the controller to wake-up due to activity on the RX/DT line. This feature is available only in Asynchronous mode.

The auto-wake-up feature is enabled by setting the WUE bit of the BAUDCON register. Once set, the normal receive sequence on RX/DT is disabled, and the EUSART remains in an Idle state, monitoring for a wake-up event independent of the CPU mode. A wake-up event consists of a high-to-low transition on the RX/DT line. (This coincides with the start of a Sync Break or a wake-up signal character for the LIN protocol.)

The EUSART module generates an RCIF interrupt coincident with the wake-up event. The interrupt is generated synchronously to the Q clocks in normal CPU operating modes (Figure 21-7), and asynchronously if the device is in Sleep mode (Figure 21-8). The interrupt condition is cleared by reading the RCREG register.

The WUE bit is automatically cleared by the low-to-high transition on the RX line at the end of the Break. This signals to the user that the Break event is over. At this point, the EUSART module is in Idle mode waiting to receive the next character.

21.4.3.1 Special Considerations

Break Character

To avoid character errors or character fragments during a wake-up event, the wake-up character must be all zeros.

When the wake-up is enabled, the function works independent of the low time on the data stream. If the WUE bit is set and a valid non-zero character is received, the low time from the Start bit to the first rising edge will be interpreted as the wake-up event. The remaining bits in the character will be received as a fragmented character and subsequent characters can result in framing or overrun errors.

Therefore, the initial character in the transmission must be all '0's. This must be ten or more bit times; 13-bit times are recommended for LIN bus or any number of bit times for standard RS-232 devices.

Oscillator Start-up Time

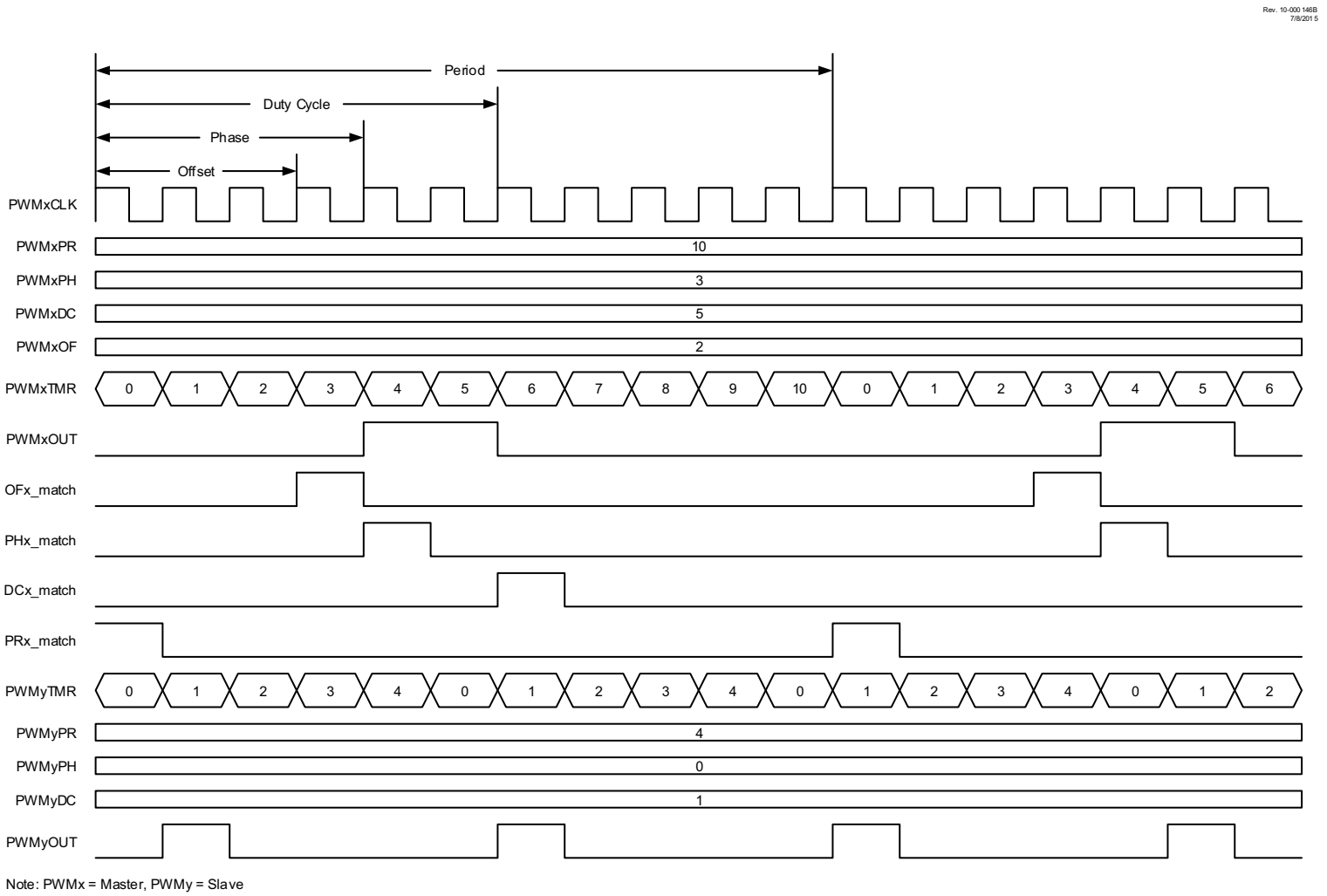
Oscillator start-up time must be considered, especially in applications using oscillators with longer start-up intervals (i.e., LP, XT or HS/PLL mode). The Sync Break (or wake-up signal) character must be of sufficient length, and be followed by a sufficient interval, to allow enough time for the selected oscillator to start and provide proper initialization of the EUSART.

WUE Bit

The wake-up event causes a receive interrupt by setting the RCIF bit. The WUE bit is cleared in hardware by a rising edge on RX/DT. The interrupt condition is then cleared in software by reading the RCREG register and discarding its contents.

To ensure that no actual data is lost, check the RCIDL bit to verify that a receive operation is not in process before setting the WUE bit. If a receive operation is not occurring, the WUE bit may then be set just prior to entering the Sleep mode.

FIGURE 22-8: INDEPENDENT RUN MODE TIMING DIAGRAM



Note: PWMx = Master, PWMy = Slave

FIGURE 22-9: SLAVE RUN MODE WITH SYNC START TIMING DIAGRAM

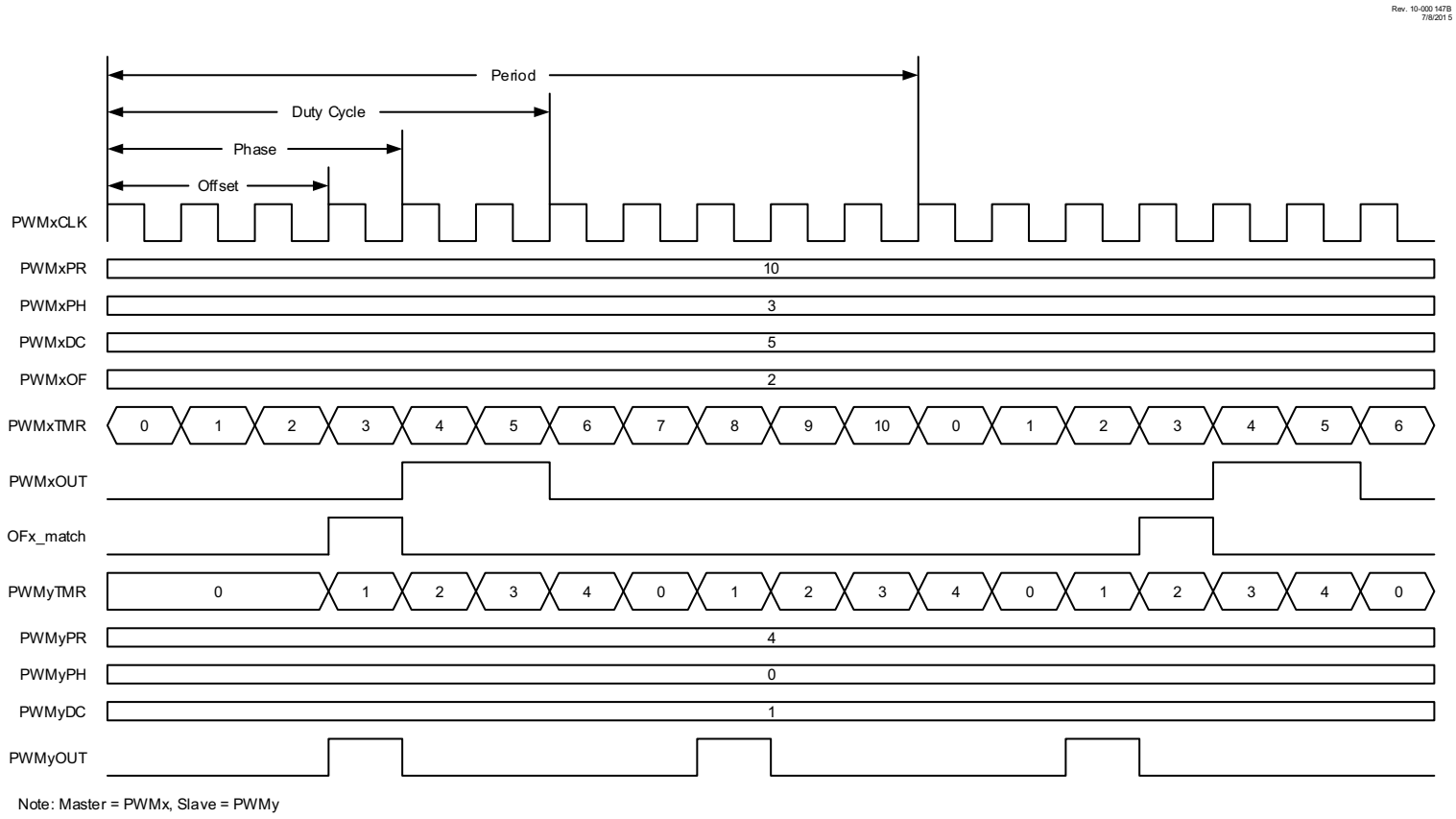
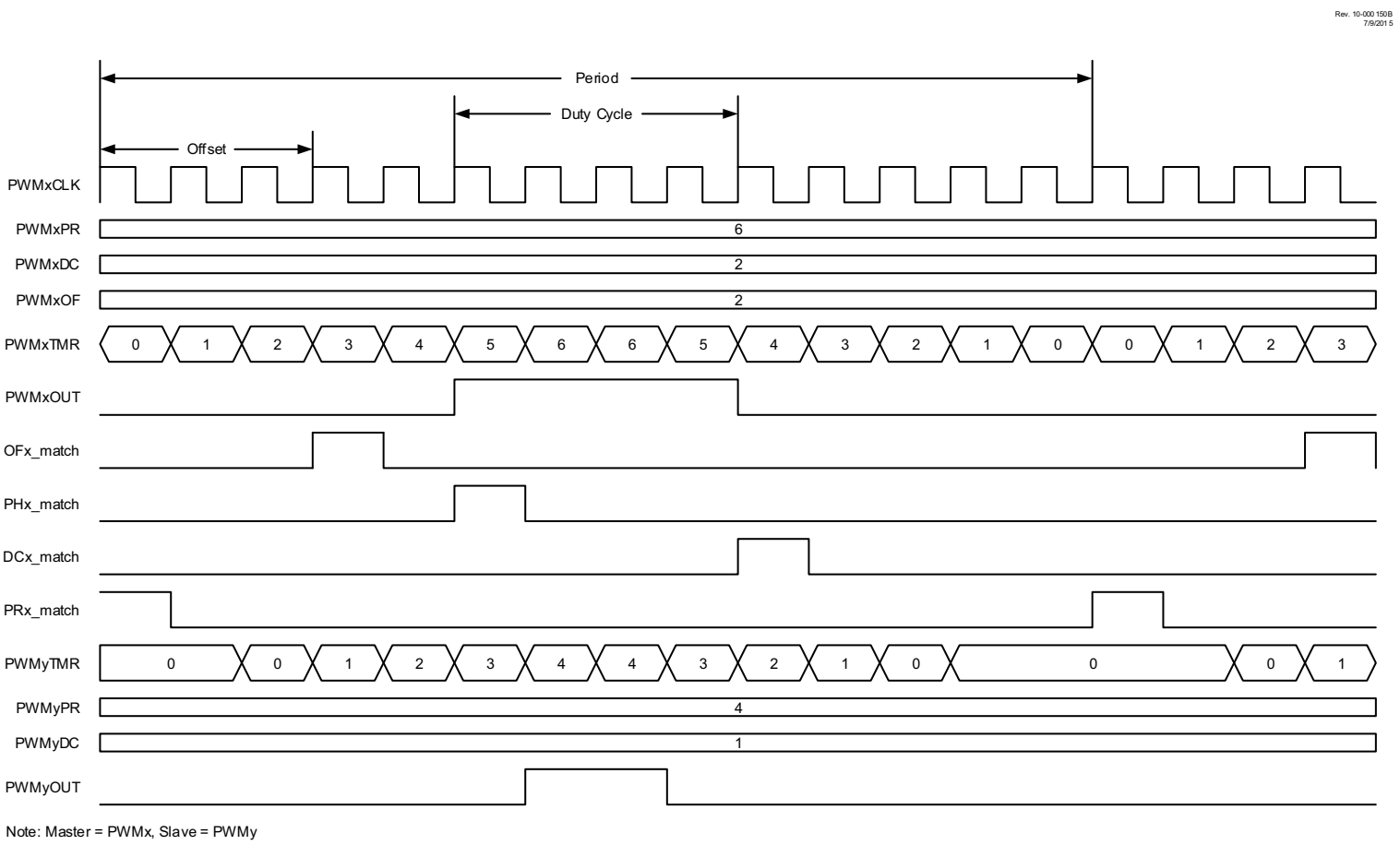


FIGURE 22-12: OFFSET MATCH ON INCREMENTING TIMER TIMING DIAGRAM



REGISTER 22-7: PWMxPHH: PWMx PHASE COUNT HIGH REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
PH<15:8>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	
u = Bit is unchanged	x = Bit is unknown	U = Unimplemented bit, read as ‘0’
‘1’ = Bit is set	‘0’ = Bit is cleared	-n/n = Value at POR and BOR/Value at all other Resets

bit 7-0 **PH<15:8>**: PWMx Phase High bits
Upper eight bits of PWM phase count.

REGISTER 22-8: PWMxPHL: PWMx PHASE COUNT LOW REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
PH<7:0>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	
u = Bit is unchanged	x = Bit is unknown	U = Unimplemented bit, read as ‘0’
‘1’ = Bit is set	‘0’ = Bit is cleared	-n/n = Value at POR and BOR/Value at all other Resets

bit 7-0 **PH<7:0>**: PWMx Phase Low bits
Lower eight bits of PWM phase count.

FIGURE 23-5: SHUTDOWN FUNCTIONALITY, AUTO-RESTART DISABLED (GxARSEN = 0, GxASDLA = 01, GxASDLB = 01)

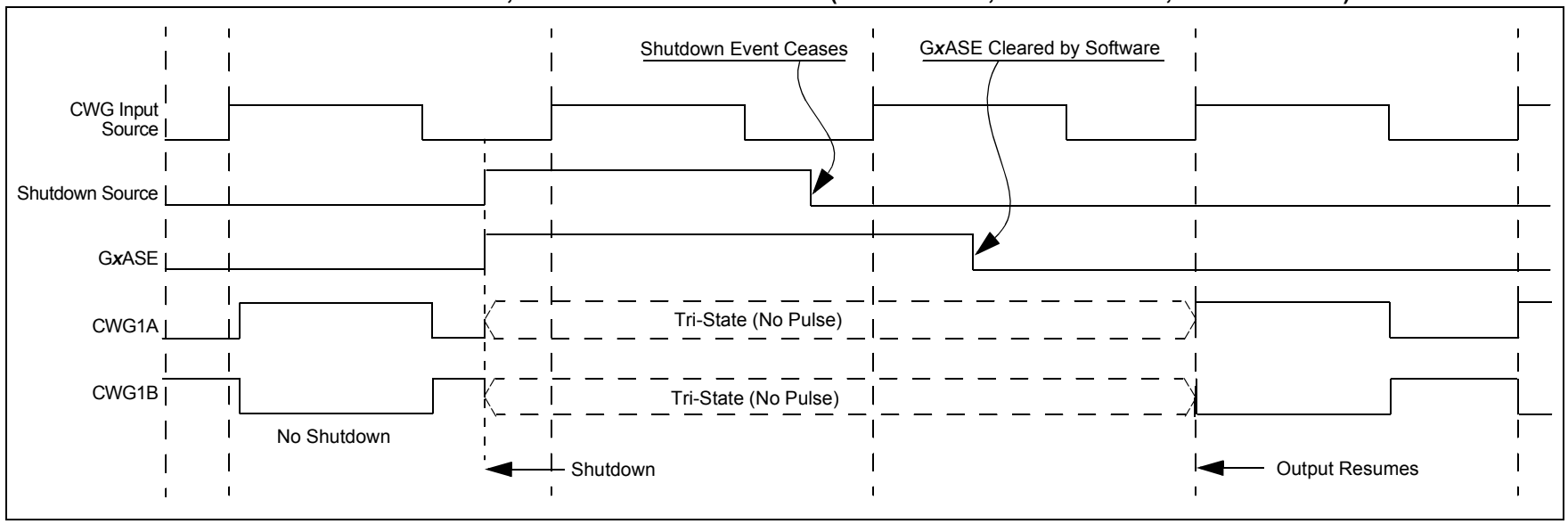


FIGURE 23-6: SHUTDOWN FUNCTIONALITY, AUTO-RESTART ENABLED (GxARSEN = 1, GxASDLA = 01, GxASDLB = 01)

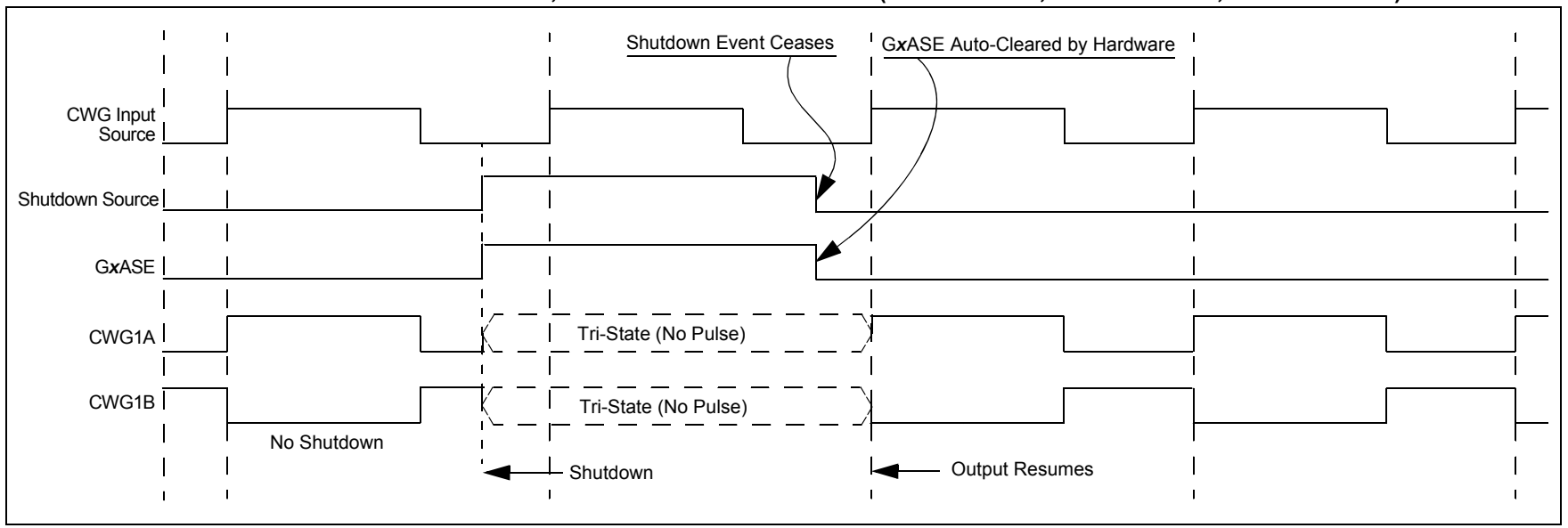


TABLE 25-3: ENHANCED MID-RANGE INSTRUCTION SET (CONTINUED)

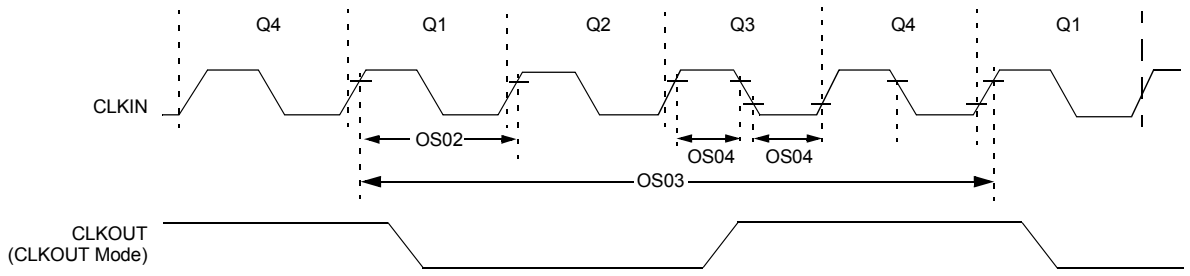
Mnemonic, Operands		Description	Cycles	14-Bit Opcode MSb	LSb	Status Affected	Notes
CONTROL OPERATIONS							
BRA	k	Relative Branch	2	11 001k kkkk kkkk			
BRW	–	Relative Branch with W	2	00 0000 0000 1011			
CALL	k	Call Subroutine	2	10 0kkk kkkk kkkk			
CALLW	–	Call Subroutine with W	2	00 0000 0000 1010			
GOTO	k	Go to address	2	10 1kkk kkkk kkkk			
RETFIE	k	Return from interrupt	2	00 0000 0000 1001			
RETLW	k	Return with literal in W	2	11 0100 kkkk kkkk			
RETURN	–	Return from Subroutine	2	00 0000 0000 1000			
INHERENT OPERATIONS							
CLRWDT	–	Clear Watchdog Timer	1	00 0000 0110 0100		$\overline{TO}$, $\overline{PD}$	
NOP	–	No Operation	1	00 0000 0000 0000			
OPTION	–	Load OPTION_REG register with W	1	00 0000 0110 0010			
RESET	–	Software device Reset	1	00 0000 0000 0001			
SLEEP	–	Go into Standby mode	1	00 0000 0110 0011		$\overline{TO}$, $\overline{PD}$	
TRIS	f	Load TRIS register with W	1	00 0000 0110 0fff			
C COMPILER OPTIMIZED							
ADDFSR	n, k	Add Literal k to FSRn	1	11 0001 0nkk kkkk			
MOVIW	n mm	Move Indirect FSRn to W with pre/post inc/dec modifier, mm	1	00 0000 0001 0nmm	kkkk	Z	**2, 3**
	k[n]	Move INDFn to W, Indexed Indirect.	1	11 1111 0nkk 1nmm		Z	**2**
MOVWI	n mm	Move W to Indirect FSRn with pre/post inc/dec modifier, mm	1	00 0000 0001 kkkk			**2, 3**
	k[n]	Move W to INDFn, Indexed Indirect.	1	11 1111 1nkk			**2**

Note 1: If the Program Counter (PC) is modified, or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a `NOP`.

2: If this instruction addresses an INDF register and the MSb of the corresponding FSR is set, this instruction will require one additional instruction cycle.

3: See the table in the `MOVIW` and `MOVWI` instruction descriptions.

FIGURE 26-5: CLOCK TIMING



Note 1: See Table 26-10.

TABLE 26-7: CLOCK OSCILLATOR TIMING REQUIREMENTS

Standard Operating Conditions (unless otherwise stated)							
Param. No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
OS01	FOSC	External CLKIN Frequency(1)	DC	—	0.5	MHz	External Clock (ECL)
			DC	—	4	MHz	External Clock (ECM)
			DC	—	20	MHz	External Clock (ECH)
OS02	TOSC	External CLKIN Period(1)	50	—	∞	ns	External Clock (EC)
OS03	TCY	Instruction Cycle Time(1)	200	TCY	DC	ns	TCY = 4/FOSC

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, +25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min" values with an external clock applied to the CLKIN pin. When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

TABLE 26-15: COMPARATOR SPECIFICATIONS(1)

Operating Conditions (unless otherwise stated) V_{DD} = 3.0V, T_A = +25°C							
Param. No.	**Sym.**	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Comments**
CM01	VIOFF	Input Offset Voltage	—	±7.5	±60	mV	CxSP = 1, VICM = VDD/2
CM02	VICM	Input Common-Mode Voltage	0	—	VDD	V	
CM03	CMRR	Common-Mode Rejection Ration	—	50	—	dB	
CM04A	TRESP(2)	Response Time Rising Edge	—	400	800	ns	CxSP = 1
CM04B		Response Time Falling Edge	—	200	400	ns	CxSP = 1
CM04C		Response Time Rising Edge	—	1200	—	ns	CxSP = 0
CM04D		Response Time Falling Edge	—	550	—	ns	CxSP = 0
CM05*	TMC2OV	Comparator Mode Change to Output Valid	—	—	10	μs	
CM06	CHYSTER	Comparator Hysteresis	—	25	—	mV	CxHYS = 1, CxSP = 1

* These parameters are characterized but not tested.

Note 1: See **Section 27.0 "DC and AC Characteristics Graphs and Charts"** for operating characterization.

2: Response time measured with one comparator input at VDD/2, while the other input transitions from VSS to VDD.

TABLE 26-16: DIGITAL-TO-ANALOG CONVERTER (DAC) SPECIFICATIONS(1)

Operating Conditions (unless otherwise stated) V_{DD} = 3.0V, T_A = +25°C							
Param. No.	**Sym.**	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Comments**
DAC01*	CLSB	Step Size	—	VDD/32	—	V	
DAC02*	CACC	Absolute Accuracy	—	—	± 1/2	LSb	
DAC03*	CR	Unit Resistor Value (R)	—	5K	—	Ω	
DAC04*	CST	Settling Time(2)	—	—	10	μs	

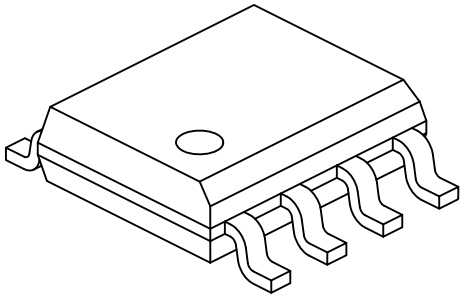
* These parameters are characterized but not tested.

Note 1: See **Section 27.0 "DC and AC Characteristics Graphs and Charts"** for operating characterization.

2: Settling time measured while DACR<4:0> transitions from '0000' to '1111'.

8-Lead Plastic Small Outline (SN) - Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		8	
Pitch	e		1.27 BSC	
Overall Height	A	-	-	1.75
Molded Package Thickness	A2	1.25	-	-
Standoff §	A1	0.10	-	0.25
Overall Width	E		6.00 BSC	
Molded Package Width	E1		3.90 BSC	
Overall Length	D		4.90 BSC	
Chamfer (Optional)	h	0.25	-	0.50
Foot Length	L	0.40	-	1.27
Footprint	L1		1.04 REF	
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.17	-	0.25
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

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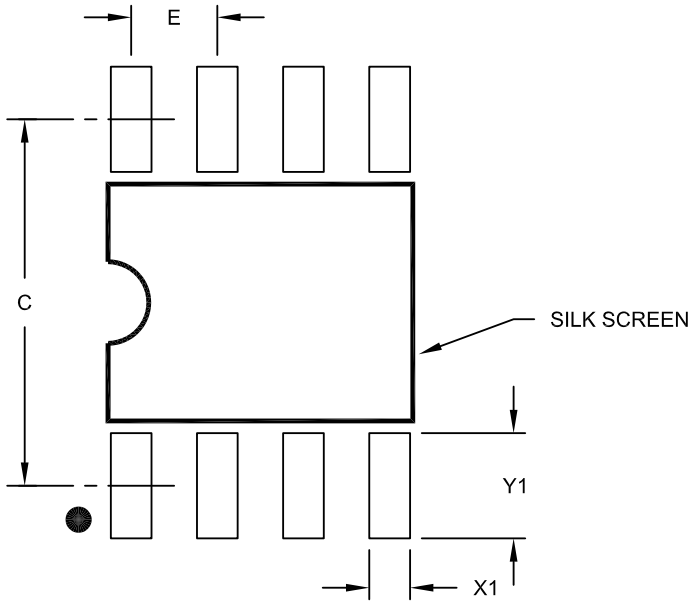
8-Lead Plastic Small Outline (SN) – Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		1.27 BSC	
Contact Pad Spacing	C		5.40	
Contact Pad Width (X8)	X1			0.60
Contact Pad Length (X8)	Y1			1.55

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2057A